

# Board Level Cooling – Extruded 5012



## BOARD LEVEL COOLING - EXTRUDED 5012

Extruded 5012 is a rectangular bi-directional board level heat sink designed to cool DIP devices. Representative image only.



## ORDERING INFORMATION

Part Number	Device Type
501200B00000G	DIP

## HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	18.57
Heat Sink Length (mm)	6.35
Heat Sink Height (mm)	4.83
Heat Sink Mounting Direction	Horizontal

## MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

